

Mounted SAM data sheet SAM- λ -A-25.0g

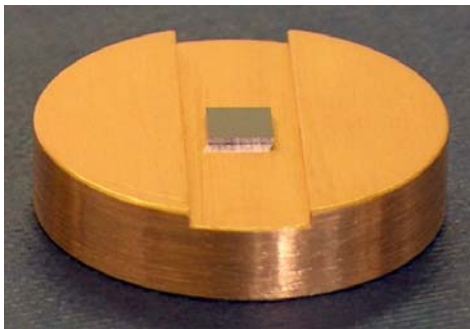
GaAs chip area	standard:	4mm x 4mm
	optional:	other dimensions on request
Chip thickness	standard:	400 μm
	optional:	150 μm

Front side protection the SAM is protected with a dielectric front layer.

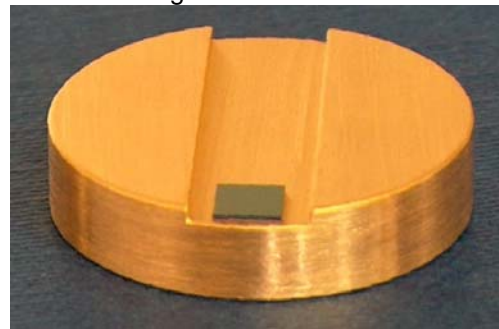
The SAM chip is glued on a gold plated Cu-cylinder with 25.0 mm \varnothing using a thermal conducting paste.

- The **standard** position of the SAM is at the center of the mount.
- **Optional** the SAM can be mounted at the edge of the mount without extra charges.

Center mounted SAM



Edge mounted SAM



Mount

Cu-cylinder, $\varnothing = 25.0 \text{ mm}$
 $l = 6.0 \text{ mm}$

